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## ABSTRACT OF THE DISCLOSURE

The present invention provides an electrically conductive layer  
5 comprising a copper alloy which includes at least one of Ag, As, Bi, P, Sb,  
Si, and Ti in the range of not less than 0.1 percent by weight to not more  
than a maximum solubility limit to copper, so that the copper alloy is in a  
solid solution and/or which includes at least one of Mo, Ta and W in a  
range of not less than 0.1 percent by weight to not more than 1 percent by  
10 weight.